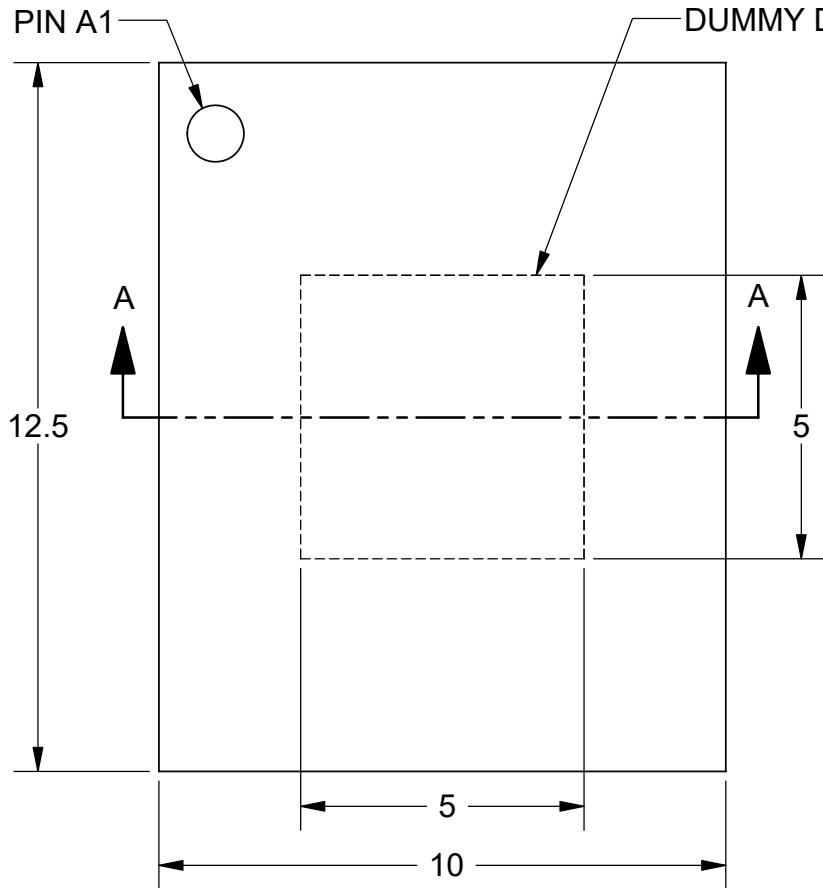
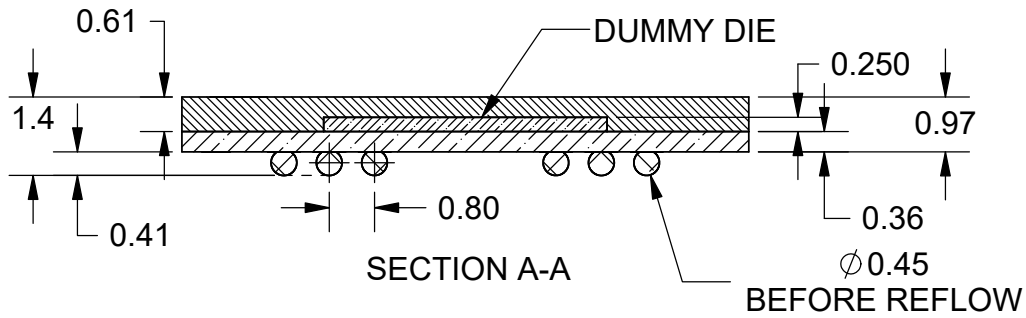
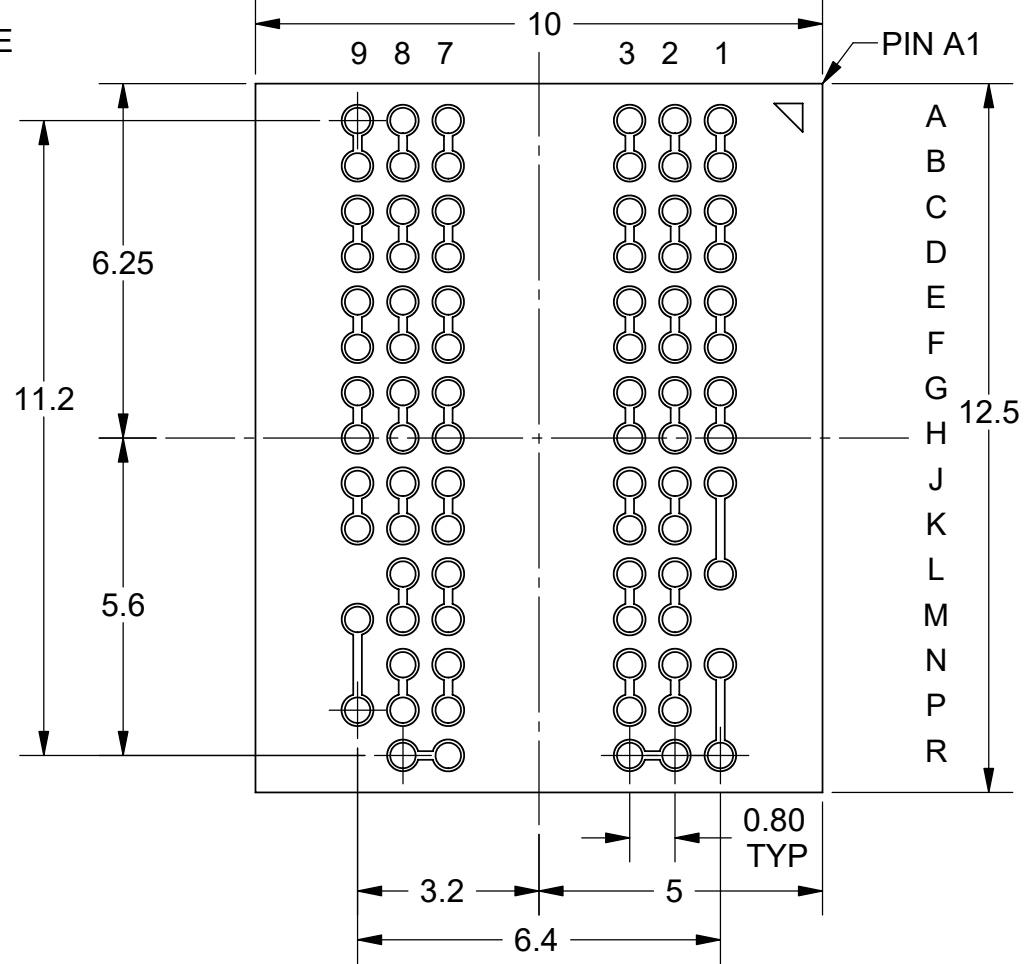


TOP VIEW



BALL VIEW



Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.36mm (14 mil).
- 5) PAD Cu DIAMETER: 0.56mm (22 mil).
- 6) SUBSTRATE MATERIAL: FR4.
- 7) DUMMY DIE: 0.25mm (10 mil) THICK.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA84T.8C-DC654D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA84T.8-DC654D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS	DATE
X.X	+/- 0.1	DRAWN J. Hines	4/21/2011
X.XX	+/- 0.05		
X.XXX	+/- 0.025		
ANGLES +/- 0.5°		ENG	
ALL DIMENSIONS IN		MFG	
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA	
THIRD ANGLE PROJECTION		CUST	
		REVISED	

**TopLine**

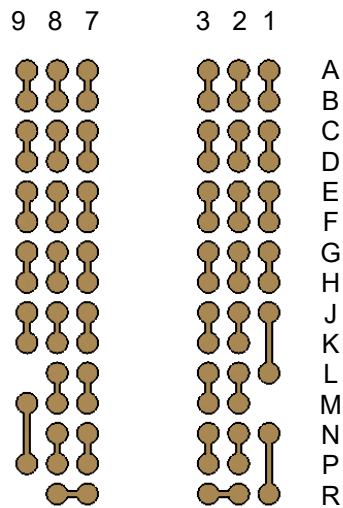
**TITLE** BGA84T.8C-DC654D  
DAISY CHAIN DUMMY

SCALE	SIZE	DRAWING NO.	REV
7.5:1	A	586651	A

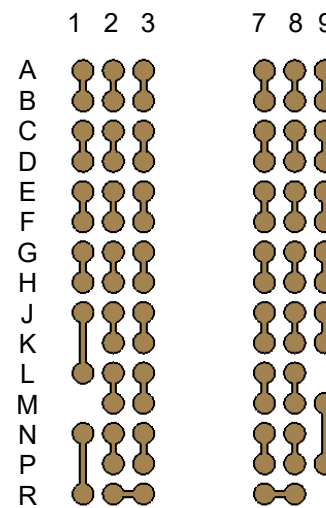
DO NOT SCALE DRAWING

SHEET 1 OF 3

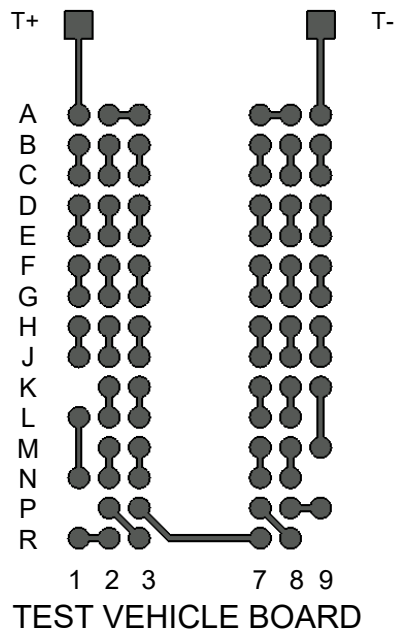
BALL VIEW



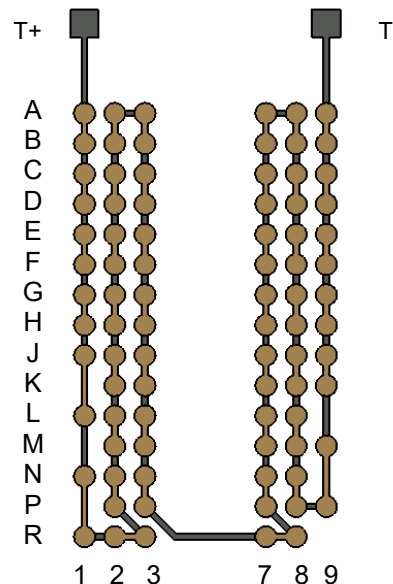
BOTTOM SIDE  
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING  
TO TEST BOARD  
(TOP X-RAY VIEW)

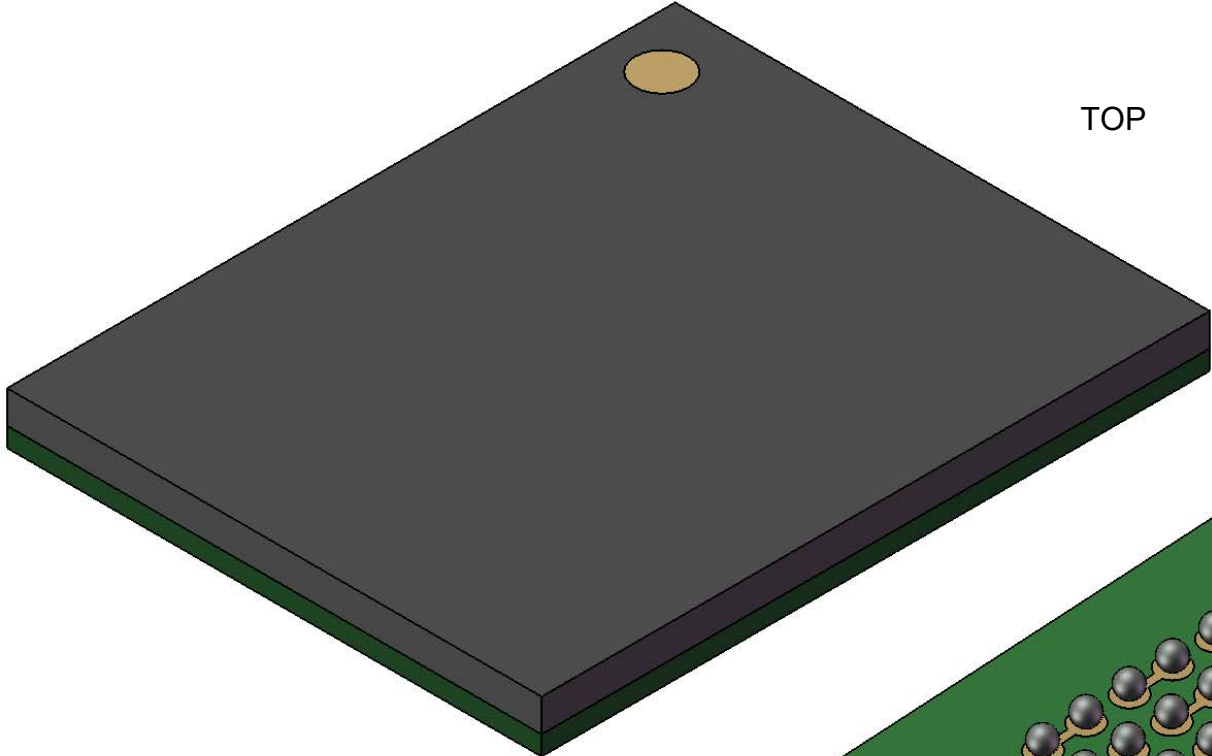


Notes:

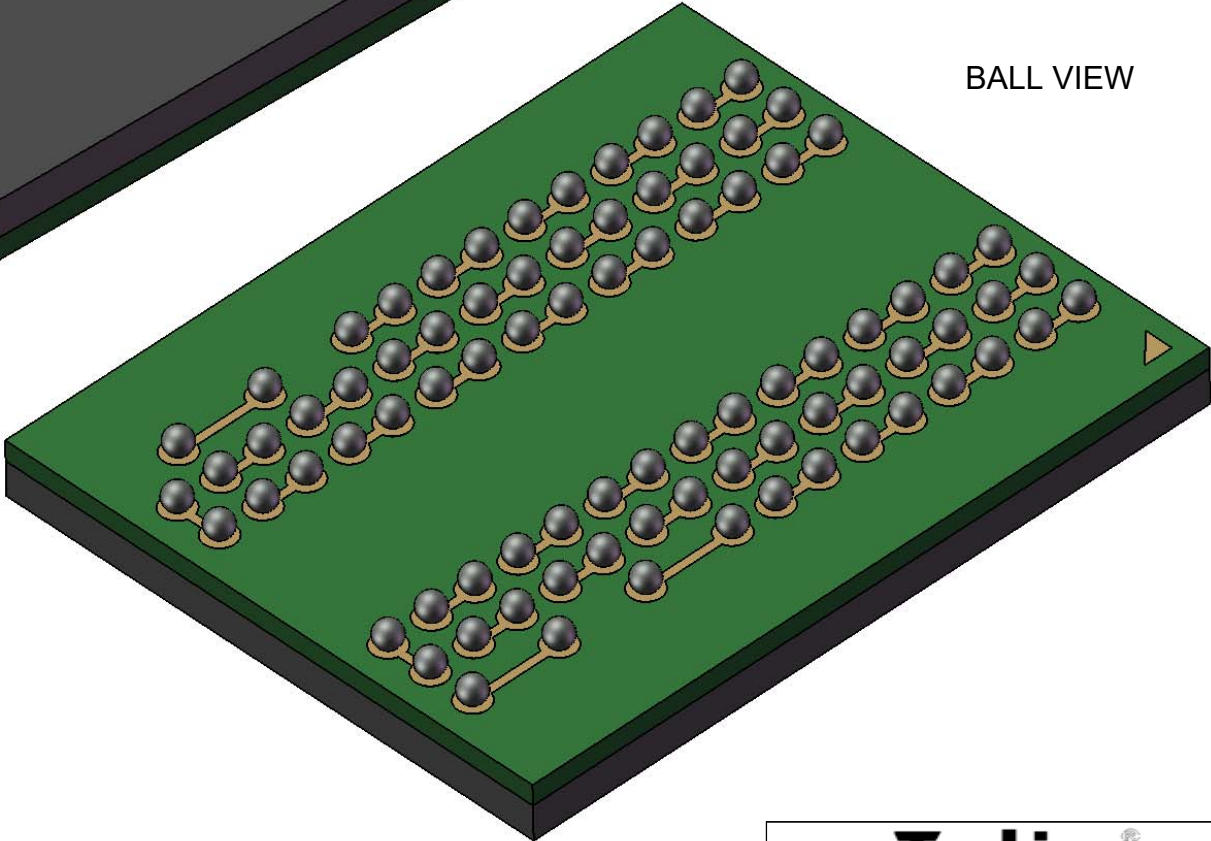
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.56mm (22mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6mil).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.36mm (14mil).

<b>TopLine</b> <sup>®</sup>			
TITLE		BGA84T.8C-DC654D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	586651	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL VIEWS



TOP



BALL VIEW

<b>TopLine</b> <sup>®</sup>			
TITLE		BGA84T.8C-DC654D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
10:1	A	586651	A
DO NOT SCALE DRAWING			SHEET 3 OF 3